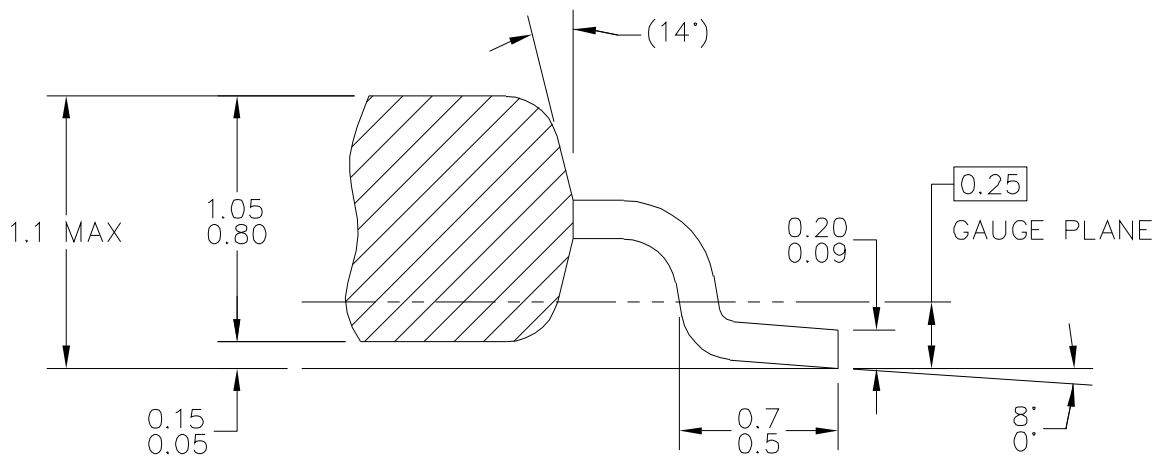
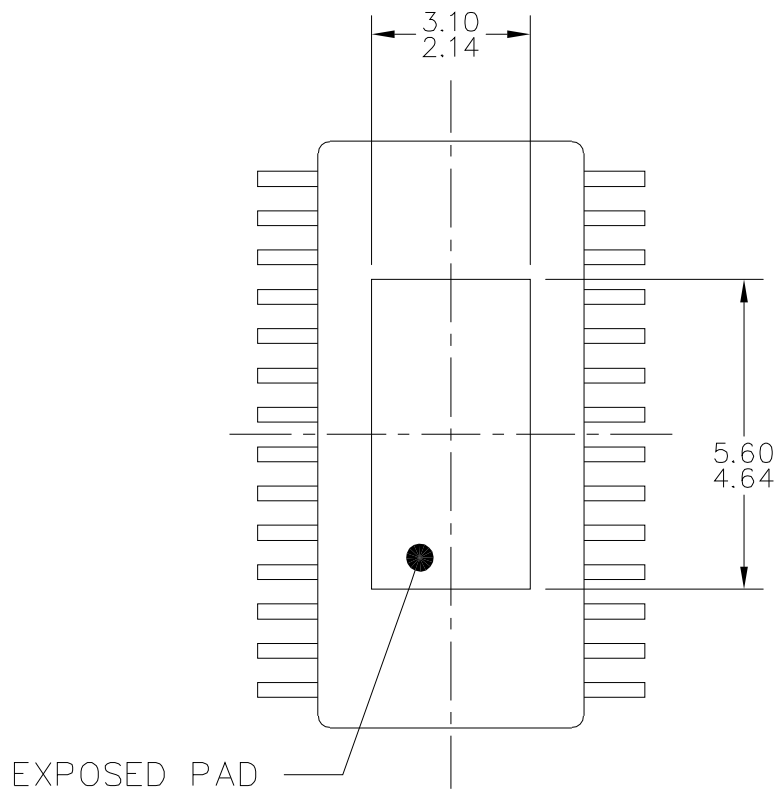


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TITLE: TSSOP, 4.4 X 9.7 X 1.025 PKG, 0.65 PITCH, 28 TERMINAL	DOCUMENT NO: 98ASA00862D	REV: C
	STANDARD: NON JEDEC	
	SOT1172-4	10 MAY 2017

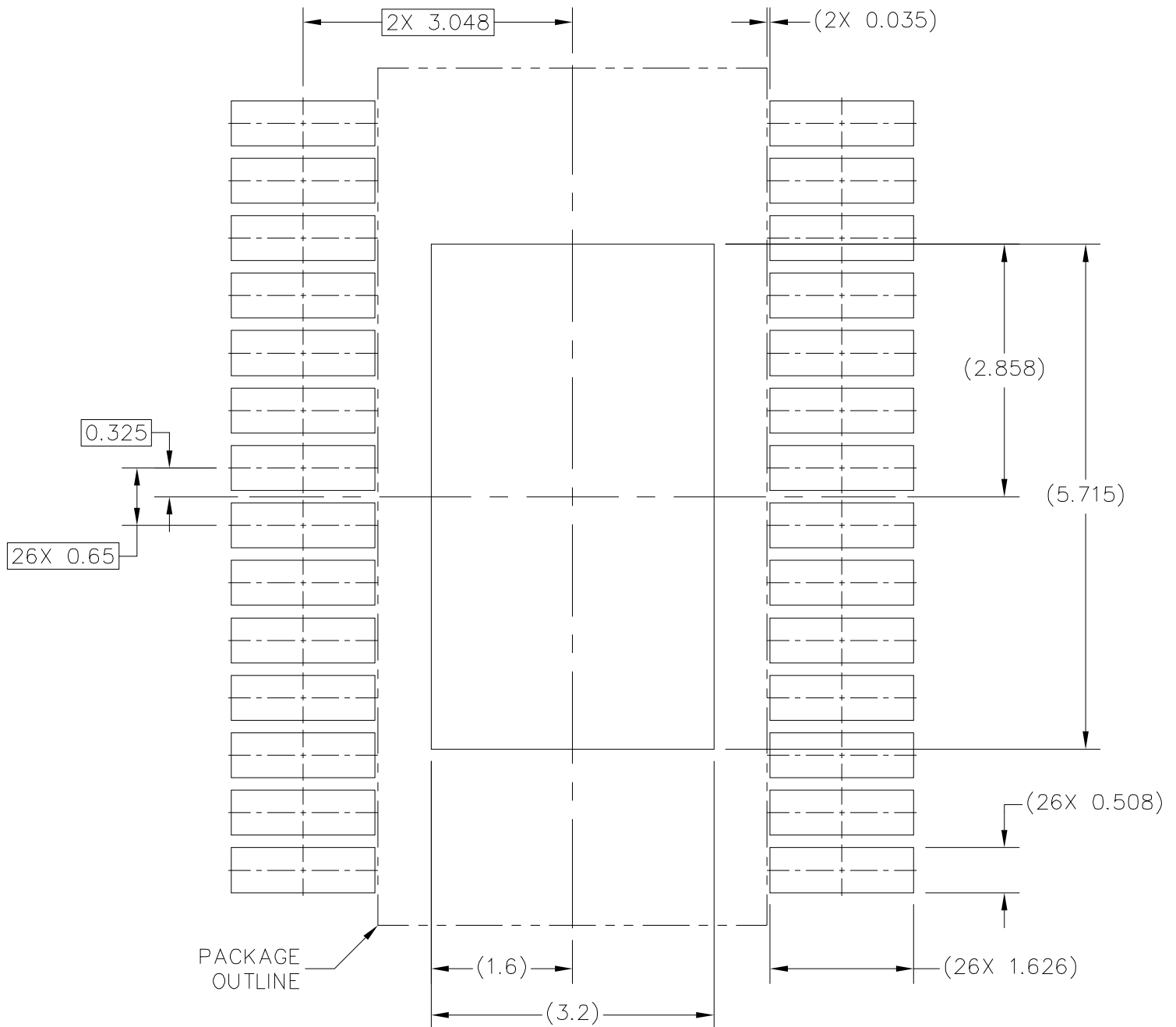


SECTION D-D



VIEW E-E

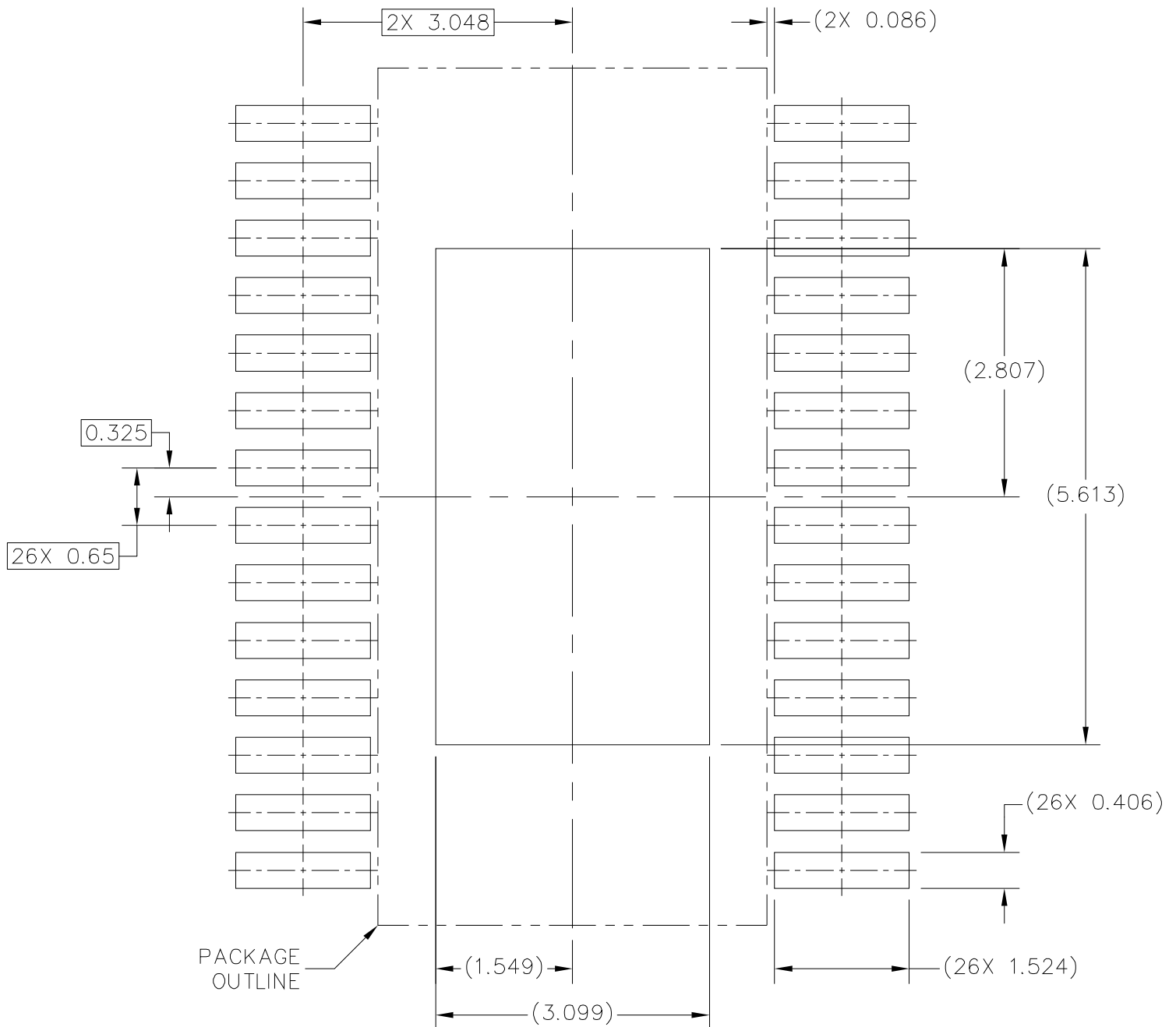
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TITLE: TSSOP, 4.4 X 9.7 X 1.025 PKG, 0.65 PITCH, 28 TERMINAL		DOCUMENT NO: 98ASA00862D	REV: C
		STANDARD: NON JEDEC	
		SOT1172-4	10 MAY 2017



## PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

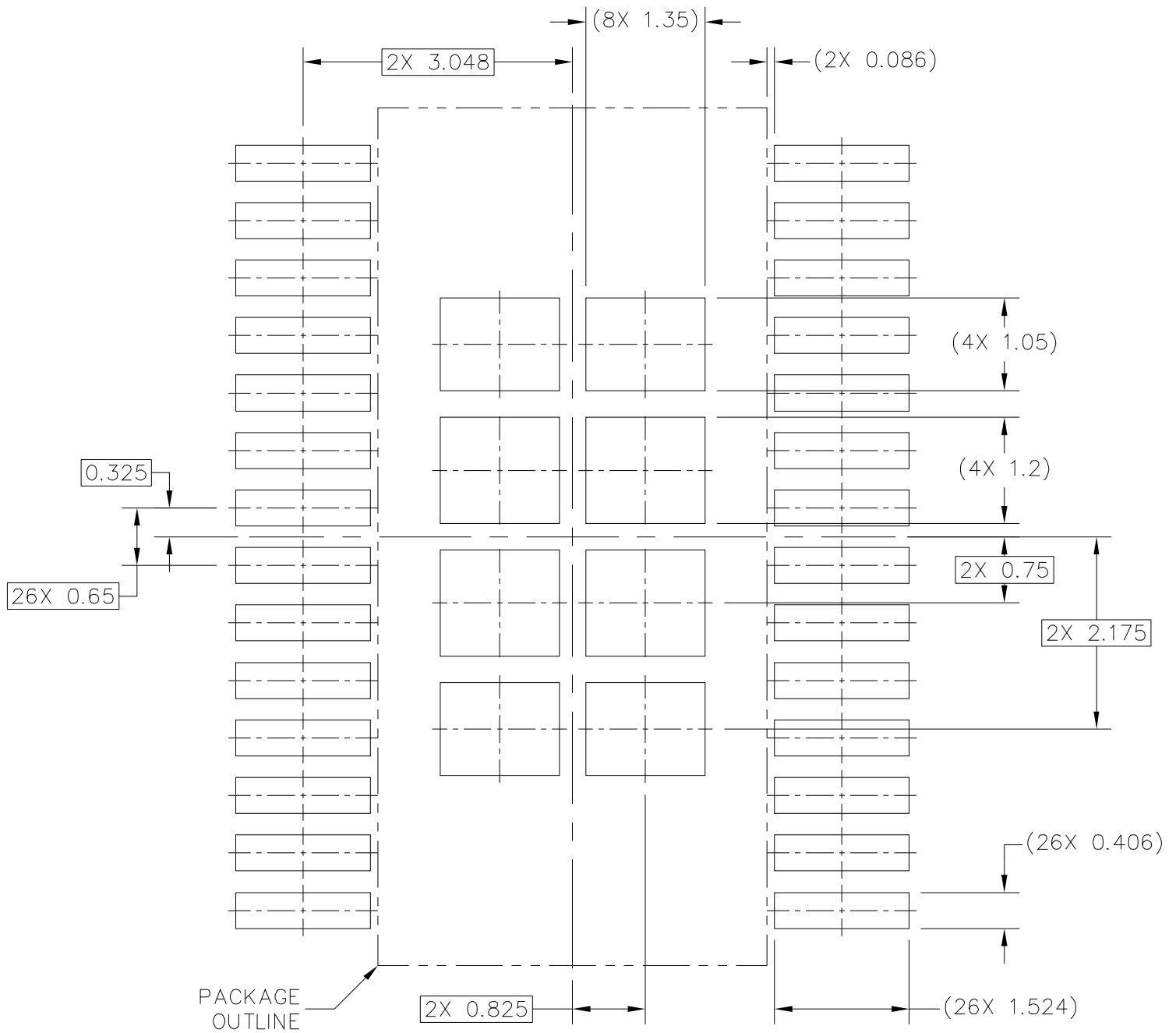
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TITLE: TSSOP, 4.4 X 9.7 X 1.025 PKG, 0.65 PITCH, 28 TERMINAL		DOCUMENT NO: 98ASA00862D	REV: C
		STANDARD: NON JEDEC	
		SOT1172-4	10 MAY 2017



## PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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TITLE: TSSOP, 4.4 X 9.7 X 1.025 PKG, 0.65 PITCH, 28 TERMINAL		DOCUMENT NO: 98ASA00862D	REV: C
		STANDARD: NON JEDEC	
		SOT1172-4	10 MAY 2017



## PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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TITLE: TSSOP, 4.4 X 9.7 X 1.025 PKG, 0.65 PITCH, 28 TERMINAL		DOCUMENT NO: 98ASA00862D	REV: C
		STANDARD: NON JEDEC	
		SOT1172-4	10 MAY 2017



NOTES:

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M–1994.

2. DIMENSIONS IN MILLIMETERS.

3. DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.15 PER END.

4. DIMENSION DOES NOT INCLUDE INTERLEAD FLASH OR MOLD PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE.

5. DIMENSION DOES NOT INCLUDE DAM BAR PROTRUSIONS. DAM BAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.38.

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TITLE: TSSOP, 4.4 X 9.7 X 1.025 PKG, 0.65 PITCH, 28 TERMINAL		DOCUMENT NO: 98ASA00862D	REV: C
		STANDARD: NON JEDEC	
		SOT1172–4	10 MAY 2017